

Product Change Notification

(Notification – P2111052-DIG)

(LLWEB-20123464 / CEN001)

November 9, 2021

To: *Our Valued Digi-Key Electronics Customer*

Overview: The purpose of this notification is to communicate a product change of select Renesas Electronics America, Inc. (REA) devices.

This notification announces the following changes for select RH850/F1 and R1 series products manufactured from Naka (wafer fab site) and RSC/Nishiki (assembly sites). See the Appendix for additional details.

1. Photomask change to revise Core Voltage Monitor circuits to the same circuits as used in TSMC product.
2. Change of bond wire material.
3. Change of mold resin.
4. Change of pad opening size.
5. Change of die-attach material.

There is a change to the part number. There is no impact to the form, fit, function, quality & reliability of the products.

Affected Products: A review of our records indicates the list of products in the Appendix may affected your company.

Part numbers given in this list are for active part numbers in REA database at the time of this notification.

Key Dates:

Shipments from REA of the devices with the new mask and assembly materials begins.
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April 1, 2022

Response: No response is required. REA will consider this notification approved 30 days after its issue. If you anticipate volumes beyond your regular rate prior to the transition date, please contact your REA sales representative with a forecast of your requirements.

If the customer provides a timely acknowledgement, the customer shall have 90 days (an additional 60 days) from the date of receipt of this notification in which to make any objections to the notification. If the customer does not make any objections to this notification within 90 days of the receipt of the notification, then Renesas will consider the notification as approved. If the customer cannot accept the notification, then the customer must provide Renesas with a last time buy demand and purchase order.

Please contact your REA sales representative for any questions or comments. Thank you for your attention.

Sincerely,

Renesas Electronics America, Inc.

Appendix A: Digi-Key Affected Part Numbers

Booking Part Number	Replacement PN	Booking Part Number	Replacement PN
R7F7010063AFP#BA4	R7F7010063AFP-C#BA4	R7F7010574AFP#KA4	R7F7010574AFP-C#KA4
R7F7010073AFP#KA4	R7F7010073AFP-C#KA4	R7F701A013AFP#KA4	R7F701A013AFP-C#KA4
R7F7010143AFP#KA2	R7F7010143AFP-C#KA2	R7F7010023AFP#BA4	R7F7010023AFP-C#BA4
R7F7010144AFP#KA2	R7F7010144AFP-C#KA2	R7F7010023AFP#KA4	R7F7010023AFP-C#KA4
R7F7010153AFP#KA2	R7F7010153AFP-C#KA2	R7F7010533AFP#KA4	R7F7010533AFP-C#KA4
R7F7010193AFP#KA2	R7F7010193AFP-C#KA2	R7F7010533AFP#KA8	R7F7010533AFP-C#KA8
R7F7010203AFP#KA2	R7F7010203AFP-C#KA2	R7F7010534AFP#KA4	R7F7010534AFP-C#KA4
R7F7010243AFP#BA2	R7F7010243AFP-C#BA2	R7F7010543AFP#KA4	R7F7010543AFP-C#KA4
R7F7010243AFP#KA2	R7F7010243AFP-C#KA2	R7F7010544AFP#BA4	R7F7010544AFP-C#BA4
R7F7010244AFP#KA2	R7F7010244AFP-C#KA2	R7F7010104AFP#KA4	R7F7010104AFP-C#KA4
R7F7010253AFP#BA2	R7F7010253AFP-C#BA2	R7F7010113AFP#BA4	R7F7010113AFP-C#BA4
R7F7010253AFP#KA2	R7F7010253AFP-C#KA2	R7F7010113AFP#KA4	R7F7010113AFP-C#KA4
R7F7010403AFP#KA2	R7F7010403AFP-C#KA2	R7F7010113AFP#KA8	R7F7010113AFP-C#KA8
R7F7010404AFP#KA2	R7F7010404AFP-C#KA2	R7F7010114AFP#BA4	R7F7010114AFP-C#BA4
R7F7010254AFP#KA2	R7F7010254AFP-C#KA2	R7F7010114AFP#KA4	R7F7010114AFP-C#KA4
R7F7010273AFP#KA4	R7F7010273AFP-C#KA4	R7F7010123AFP#BA4	R7F7010123AFP-C#BA4
R7F7010283AFP#KA4	R7F7010283AFP-C#KA4	R7F7010123AFP#KA4	R7F7010123AFP-C#KA4
R7F7010284AFP#KA4	R7F7010284AFP-C#KA4	R7F7010124AFP#KA4	R7F7010124AFP-C#KA4
R7F7010293AFP#BA4	R7F7010293AFP-C#BA4	R7F7010133AFP#KA4	R7F7010133AFP-C#KA4
R7F7010303AFP#KA4	R7F7010303AFP-C#KA4	R7F7010134AFP#KA4	R7F7010134AFP-C#KA4
R7F7010323AFP#KA4	R7F7010323AFP-C#KA4	R7F7010163AFP#KA4	R7F7010163AFP-C#KA4
R7F7010333AFP#KA4	R7F7010333AFP-C#KA4	R7F7010083AFP#BA4	R7F7010083AFP-C#BA4
R7F7010334AFP#BA4	R7F7010334AFP-C#BA4	R7F7010083AFP#KA4	R7F7010083AFP-C#KA4
R7F7010334AFP#KA4	R7F7010334AFP-C#KA4	R7F7010084AFP#KA4	R7F7010084AFP-C#KA4
R7F7010343AFP#BA4	R7F7010343AFP-C#BA4	R7F7010093AFP#KA4	R7F7010093AFP-C#KA4
R7F7010343AFP#KA4	R7F7010343AFP-C#KA4	R7F7010103AFP#KA4	R7F7010103AFP-C#KA4
R7F7010483AFP#KA4	R7F7010483AFP-C#KA4	R7F7010223AFP#BA4	R7F7010223AFP-C#BA4
R7F7010493AFP#BA4	R7F7010493AFP-C#BA4	R7F7010223AFP#KA4	R7F7010223AFP-C#KA4
R7F7010493AFP#KA4	R7F7010493AFP-C#KA4	R7F7010233AFP#BA4	R7F7010233AFP-C#BA4
R7F7010423AFP#KA2	R7F7010423AFP-C#KA2	R7F7010233AFP#KA4	R7F7010233AFP-C#KA4
R7F7010423AFP#KAT	R7F7010423AFP-C#KAT	R7F7010234AFP#BA4	R7F7010234AFP-C#BA4
R7F7010424AFP#KA2	R7F7010424AFP-C#KA2	R7F7010234AFP#KA4	R7F7010234AFP-C#KA4
R7F7010424AFP#KAT	R7F7010424AFP-C#KAT	R7F701A333AFP#BA4	R7F701A333AFP-C#BA4
R7F7010433AFP#KA2	R7F7010433AFP-C#KA2	R7F7010164AFP#KA4	R7F7010164AFP-C#KA4
R7F7010434AFP#KA2	R7F7010434AFP-C#KA2	R7F7010173AFP#KA4	R7F7010173AFP-C#KA4
R7F7010443AFP#BA2	R7F7010443AFP-C#BA2	R7F7010174AFP#BA4	R7F7010174AFP-C#BA4
R7F7010443AFP#KA2	R7F7010443AFP-C#KA2	R7F7010174AFP#KA4	R7F7010174AFP-C#KA4
R7F7010453AFP#BA2	R7F7010453AFP-C#BA2	R7F7010183AFP#KA4	R7F7010183AFP-C#KA4
R7F7010453AFP#KA2	R7F7010453AFP-C#KA2	R7F7010184AFP#KA4	R7F7010184AFP-C#KA4
R7F7010454AFP#KA2	R7F7010454AFP-C#KA2	R7F701A383AFP#BA4	R7F701A383AFP-C#BA4
R7F7010463AFP#KA4	R7F7010463AFP-C#KA4	R7F7010713AFP#BA4	R7F7010713AFP-C#BA4
R7F7010473AFP#KA4	R7F7010473AFP-C#KA4	R7F7010713AFP#KA4	R7F7010713AFP-C#KA4
R7F7010553AFP#KA4	R7F7010553AFP-C#KA4	R7F7010673AFP#KA4	R7F7010673AFP-C#KA4
R7F7010563AFP#KA4	R7F7010563AFP-C#KA4	R7F701A033AFP#KA8	R7F701A033AFP-C#KA8
R7F7010564AFP#KA4	R7F7010564AFP-C#KA4	R7F701A223AFP#BA4	R7F701A223AFP-C#BA4
R7F7010573AFP#KA4	R7F7010573AFP-C#KA4		

Appendix B: Change Summary for RSC Assembled Material

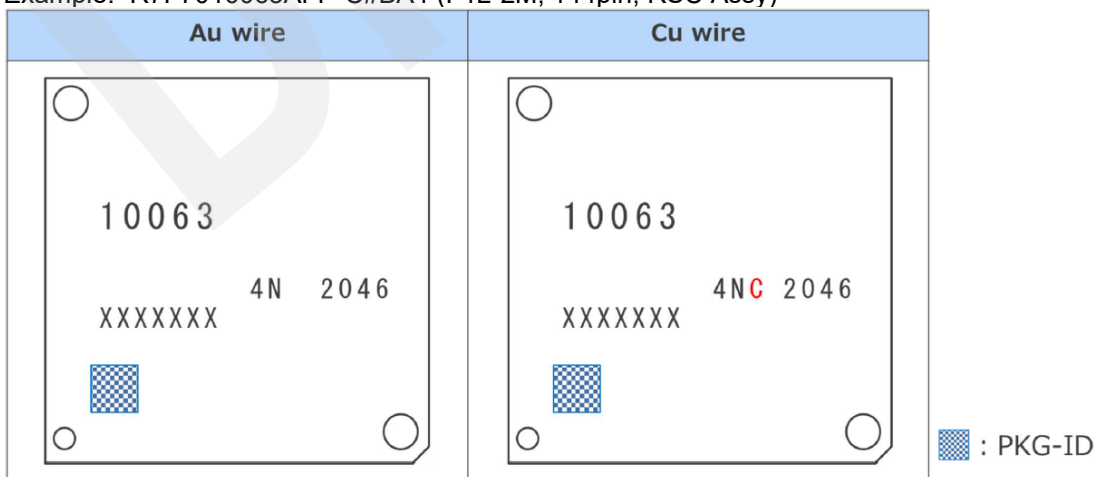
Item	Current	Change (New)
Core Voltage Monitor Circuits (48, 64, 80 & 100 pin)	Current circuit	Same as circuit as product from TSMC
Wire Bond Materials	Au Wire, φ18um	Cu wire, φ20um
Mold Resin	Mold Resin for Au Wire	Mold Resin for Cu Wire
Pad Opening Size	50um	55um
Die-Attach Material (48 & 64 pin)	Conventional Material	Renesas Standard Material (RH850 Common Material)

Appendix C: Change Summary for Nishiki Assembled Material

Item	Current	Change (New)
Core Voltage Monitor Circuits (64, 80, & 100 pin)	Current circuit	Same as circuit as product from TSMC
Wire Bond Materials	Au Wire, φ18um	Cu wire, φ20um
Mold Resin	Mold Resin for Au Wire	Mold Resin for Cu Wire
Pad Opening Size	50um	55um
Die-Attach Material (80, 100 & 144 pin)	Conventional Material	Renesas Standard Material (RH850 Common Material)

Appendix D: Product Identification (Top Mark)

Example: R7F7010063AFP-C#BA4 (F1L-2M, 144pin, RSC Assy)

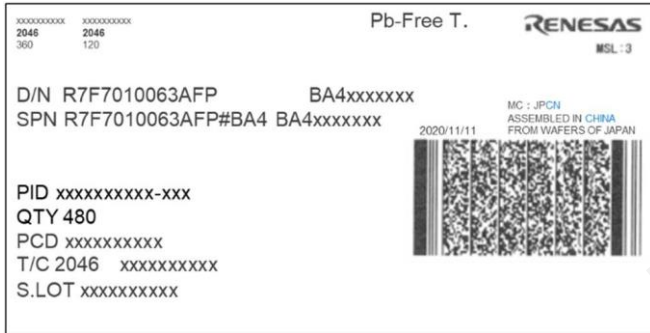


For the laser mark of Cu-wire products, "C" is added to the mark (red character).

Appendix E: Product Identification (Label)

Example: R7F7010063AFP-C#BA4 (F1L-2M, 144pin, RSC Assy)

Current Label



New Label



Red characters indicate Cu-wire product.